



Statement of Materials, Construction

LEAD-FREE -- 16L-PDIP -- TABLE OF MATERIAL DECLARATION								
No.	Component Name	Material Name	Component Weight (grams)	Materials Analysis (Element / Compound)	CAS Number	Material Mass (Gram)	Material Weight % (of Total Pkg)	Material Weight % (of Component)
1	Leadframe	Copper Alloy	0.32024	Cu	7440-50-8	0.31131	29.15452	97.213
				Fe	7439-89-6	0.00753	0.70477	2.35
				Pb	7439-92-1	0.00010	0.00900	0.03
				P	7723-14-0	0.00026	0.02474	0.0825
				Zn	7440-66-6	0.00040	0.03749	0.125
				Ag	7440-22-4	0.00064	0.05998	0.2
2	Die	Silicon Chip	0.00250	Si	7440-21-3	0.00250	0.23401	99.95
3	Die attach material	Conductive Epoxy	0.00051	Epoxy resin (5-25)	Proprietary	0.00008	0.00716	15
				Silver (70-85)	7440-21-3	0.00041	0.03797	79.5
				Aromatic Amine (1-10)	Proprietary	0.00003	0.00263	5.5
4	Wire	Gold	0.00040	Au	7440-57-5	0.00040	0.03746	99.99
5	Lead Finish	Tin	0.02593	Sn	7440-31-5	0.02593	2.42833	100
6	Encapsulation	Epoxy Resin	0.71823	Fused Silica	7631-86-9	0.48121	45.06552	67
				Epoxy resin	29690-82-2	0.14365	13.45239	20
				Phenol Resin	9003-35-4	0.05387	5.04465	7.5
				Antimony trioxide	1309-64-4	0.02155	2.01786	3
				Brominated Epoxy Resin	40039-93-8	0.01436	1.34524	2
				Carbon Black	1333-86-4	0.00215	0.20179	0.3
Total Package weight			1.06781					

Note: Component Weight based on assembly of generic parts.

Conclusion:

The analysis table above shows that this package meets the following RoHS requirements for EACH PACKAGE COMPONENT (mold compound, lead frame, etc.)

	Maximum Allowable Limit (ppm)	Maximum Allowable Limit (wt %)
Lead	1000 ppm	0.10%
Mercury	1000 ppm	0.10%
Cadmium	100 ppm	0.01%
Hexavalent Chromium	1000 ppm	0.10%

Polybrominated Biphenyls (PBB)
Polybrominated Biphenylethers (PBDE)

1000 ppm
1000 ppm

0.10%
0.10%

